

STN	Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 3-302: Zisťovanie väd pokovovania na neosadených doskách plošných spojov počítačovou tomografiou (CT)	STN EN IEC 61189-3-302 34 6513
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-302: Detection of plating defects in unpopulated circuit boards by computed tomography (CT)

Táto norma obsahuje anglickú verziu európskej normy.

This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 03/26

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 61189-3-302

November 2025

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English Version

**Test methods for electrical materials, printed boards and other
interconnection structures and assemblies - Part 3-302:
Detection of plating defects in unpopulated circuit boards by
computed tomography (CT)
(IEC 61189-3-302:2025)**

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 3-302: Détection des défauts de
métallisation dans les cartes de circuits imprimés nus par
tomographie informatisée (TI)
(IEC 61189-3-302:2025)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 3-
302: Computertomographisches Verfahren (CT) zur
Detektion von Metallisierungsfehlern in unbestückten
Leiterplatten
(IEC 61189-3-302:2025)

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CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61189-3-302:2025 (E)**European foreword**

The text of document 91/2060/FDIS, future edition 1 of IEC 61189-3-302, prepared by TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-3-302:2025.

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ISO 15708-1:2024 NOTE Approved as EN ISO 15708-1:2024 (not modified)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
ISO 15708-3	-	Non-destructive testing - Radiation methods for computed tomography - Part 3: Operation and interpretation	EN ISO 15708-3	-



IEC 61189-3-302

Edition 1.0 2025-10

INTERNATIONAL STANDARD

**Test methods for electrical materials, printed boards and other interconnection structures and assemblies -
Part 3-302: Detection of plating defects in unpopulated circuit boards by
computed tomography (CT)**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**Test methods for electrical materials, printed boards
and other interconnection structures and assemblies -
Part 3-302: Detection of plating defects in unpopulated
circuit boards by computed tomography (CT)**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/2060/FDIS	91/2071/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

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1 Scope

This part of IEC 61189 describes a method for the detection of plating defects in unpopulated circuit boards using computed tomography (CT).

This document is applicable to non-destructive testing of metallized holes.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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